

## CMOS Quad 2-Input NAND Schmitt Triggers

High-Voltage Types (20 Volt Rating)

■ CD4093B consists of four Schmitt-trigger circuits. Each circuit functions as a two-input NAND gate with Schmitt-trigger action on both inputs. The gate switches at different points for positive- and negative-going signals. The difference between the positive voltage ( $V_P$ ) and the negative voltage ( $V_N$ ) is defined as hysteresis voltage ( $V_H$ ) (see Fig. 2).

The CD4093B types are supplied in 14-lead hermetic dual-in-line ceramic packages (F3A suffix), 14-lead dual-in-line plastic packages (E suffix), 14-lead small-outline packages (M, MT, M96, and NSR suffixes), and 14-lead thin shrink small-outline packages (PW and PWR suffixes).

### Features:

- Schmitt-trigger action on each input with no external components
- Hysteresis voltage typically 0.9 V at  $V_{DD} = 5\text{ V}$  and 2.3 V at  $V_{DD} = 10\text{ V}$
- Noise immunity greater than 50%
- No limit on input rise and fall times
- Standardized, symmetrical output characteristics
- 100% tested for quiescent current at 20 V
- Maximum input current of 1  $\mu\text{A}$  at 18 V over full package-temperature range, 100 nA at 18 V and 25°C
- 5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

### Applications:

- Wave and pulse shapers
- High-noise-environment systems
- Monostable multivibrators
- Astable multivibrators
- NAND logic



### RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges.

CHARACTERISTIC	MIN.	MAX.	UNITS
Supply Voltage Range ( $T_A = \text{Full Package Temp. Range}$ )	3	18	V

### MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, ( $V_{DD}$ )	
Voltages referenced to $V_{SS}$ Terminal	–0.5V to +20V
INPUT VOLTAGE RANGE, ALL INPUTS	–0.5V to $V_{DD} + 0.5\text{V}$
DC INPUT CURRENT, ANY ONE INPUT	$\pm 10\text{mA}$
PACKAGE THERMAL IMPEDANCE, $\theta_{JA}$ (See Note 1):	
E package	80°C/W
M package	86°C/W
NS package	76°C/W
DEVICE DISSIPATION PER OUTPUT TRANSISTOR	
FOR $T_A = \text{FULL PACKAGE-TEMPERATURE RANGE}$ (All Package Types)	100mW
OPERATING-TEMPERATURE RANGE ( $T_A$ )	–55°C to +125°C
STORAGE TEMPERATURE RANGE ( $T_{stg}$ )	–65°C to +150°C
LEAD TEMPERATURE (DURING SOLDERING):	
At distance 1/16 $\pm$ 1/32 inch (1.59 $\pm$ 0.79mm) from case for 10s max	+265°C

NOTE 1: Package thermal impedance is calculated in accordance with JESD 51-7.



\* ALL INPUTS PROTECTED BY CMOS PROTECTION NETWORK

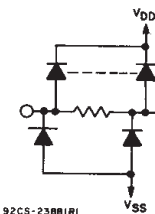


Fig. 1 – Logic diagram—1 of 4 Schmitt triggers.

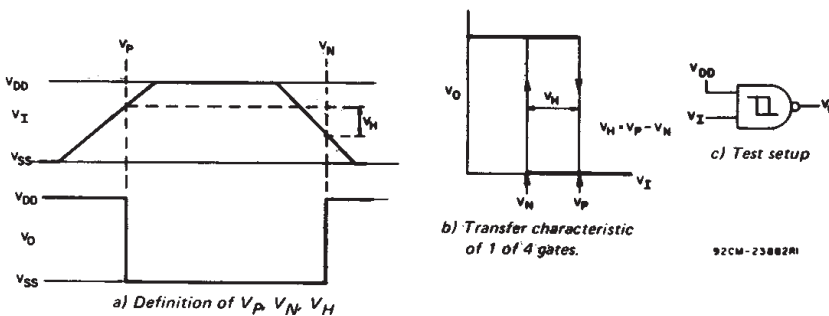


Fig. 2 – Hysteresis definition, characteristic, and test setup.

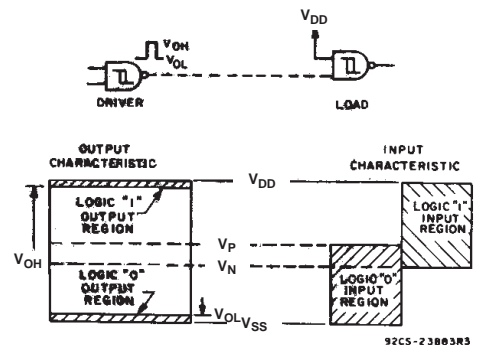


Fig. 3 – Input and output characteristics.

# CD4093B Types

## STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
	V <sub>O</sub> (V)	V <sub>IN</sub> (V)	V <sub>DD</sub> (V)	-55	-40	+85	+125	+25			
								MIN.	TYP.	MAX.	
Quiescent Device Current, I <sub>DD</sub> Max.	-	0.5	5	1	1	30	30	-	0.02	1	μA
	-	0.10	10	2	2	60	60	-	0.02	2	
	-	0.15	15	4	4	120	120	-	0.02	4	
	-	0.20	20	20	20	600	600	-	0.04	20	
Positive Trigger Threshold Voltage V <sub>p</sub> Min.	-	a	5	2.2	2.2	2.2	2.2	2.2	2.9	-	V
	-	a	10	4.6	4.6	4.6	4.6	4.6	5.9	-	
	-	a	15	6.8	6.8	6.8	6.8	6.8	8.8	-	
	-	b	5	2.6	2.6	2.6	2.6	2.6	3.3	-	
	-	b	10	5.6	5.6	5.6	5.6	5.6	7	-	
	-	b	15	6.3	6.3	6.3	6.3	6.3	9.4	-	
V <sub>p</sub> Max.	-	a	5	3.6	3.6	3.6	3.6	-	2.9	3.6	V
	-	a	10	7.1	7.1	7.1	7.1	-	5.9	7.1	
	-	a	15	10.8	10.8	10.8	10.8	-	8.8	10.8	
	-	b	5	4	4	4	4	-	3.3	4	
	-	b	10	8.2	8.2	8.2	8.2	-	7	8.2	
	-	b	15	12.7	12.7	12.7	12.7	-	9.4	12.7	
Negative Trigger Threshold Voltage V <sub>N</sub> Min.	-	a	5	0.9	0.9	0.9	0.9	0.9	1.9	-	V
	-	a	10	2.5	2.5	2.5	2.5	2.5	3.9	-	
	-	a	15	4	4	4	4	4	5.8	-	
	-	b	5	1.4	1.4	1.4	1.4	1.4	2.3	-	
	-	b	10	3.4	3.4	3.4	3.4	3.4	5.1	-	
	-	b	15	4.8	4.8	4.8	4.8	4.8	7.3	-	
V <sub>N</sub> Max.	-	a	5	2.8	2.8	2.8	2.8	-	1.9	2.8	V
	-	a	10	5.2	5.2	5.2	5.2	-	3.9	5.2	
	-	a	15	7.4	7.4	7.4	7.4	-	5.8	7.4	
	-	b	5	3.2	3.2	3.2	3.2	-	2.3	3.2	
	-	b	10	6.6	6.6	6.6	6.6	-	5.1	6.6	
	-	b	15	9.6	9.6	9.6	9.6	-	7.3	9.6	
Hysteresis Voltage V <sub>H</sub> Min.	-	a	5	0.3	0.3	0.3	0.3	0.3	0.9	-	V
	-	a	10	1.2	1.2	1.2	1.2	1.2	2.3	-	
	-	a	15	1.6	1.6	1.6	1.6	1.6	3.5	-	
	-	b	5	0.3	0.3	0.3	0.3	0.3	0.9	-	
	-	b	10	1.2	1.2	1.2	1.2	1.2	2.3	-	
	-	b	15	1.6	1.6	1.6	1.6	1.6	3.5	-	
V <sub>H</sub> Max.	-	a	5	1.6	1.6	1.6	1.6	-	0.9	1.6	V
	-	a	10	3.4	3.4	3.4	3.4	-	2.3	3.4	
	-	a	15	5	5	5	5	-	3.5	5	
	-	b	5	1.6	1.6	1.6	1.6	-	0.9	1.6	
	-	b	10	3.4	3.4	3.4	3.4	-	2.3	3.4	
	-	b	15	5	5	5	5	-	3.5	5	

<sup>a</sup> Input on terminals 1,5,8,12 or 2,6,9,13; other inputs to V<sub>DD</sub>.

<sup>b</sup> Input on terminals 1 and 2, 5 and 6, 8 and 9, or 12 and 13; other inputs to V<sub>DD</sub>.

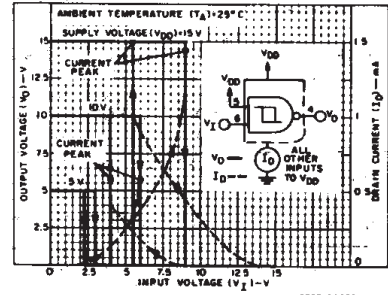


Fig. 4 - Typical current and voltage transfer characteristics.

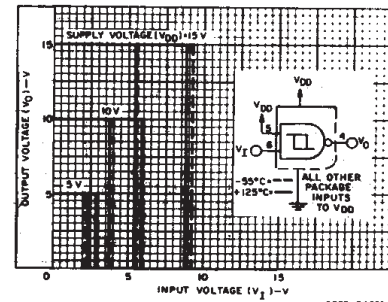


Fig. 5 - Typical voltage transfer characteristics as a function of temperature.

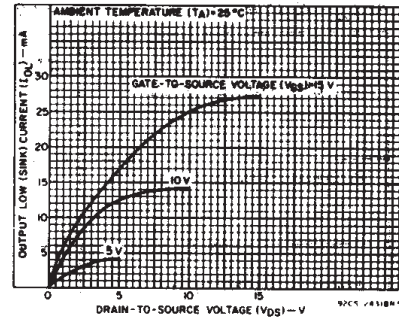


Fig. 6 - Typical output low (sink) current characteristics.

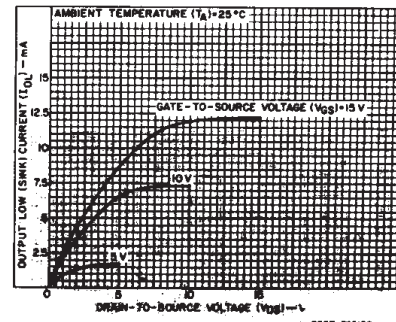


Fig. 7 - Minimum output low (sink) current characteristics.

# CD4093B Types

## STATIC ELECTRICAL CHARACTERISTICS (CONT'D)

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
	V <sub>O</sub> (V)	V <sub>IN</sub> (V)	V <sub>DD</sub> (V)	-55	-40	+85	+125	+25			
								MIN.	TYP.	MAX.	
Output Low (Sink) Current, I <sub>OL</sub> Min.	0.4	0.5	5	0.64	0.61	0.42	0.36	0.51	1	-	mA
	0.5	0.10	10	1.6	1.5	1.1	0.9	1.3	2.6	-	
	1.5	0.15	15	4.2	4	2.8	2.4	3.4	6.8	-	
Output High (Source) Current, I <sub>OH</sub> Min.	4.6	0.5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	-	mA
	2.5	0.5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	-	
	9.5	0.10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	-	
	13.5	0.15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	-	
Output Voltage Low-Level, V <sub>OL</sub> Max.	-	0.5	5	0.05			-	0	0.05	-	V
	-	0.10	10	0.05			-	0	0.05	-	
	-	0.15	15	0.05			-	0	0.05	-	
Output Voltage High-Level, V <sub>OH</sub> Min.	-	0.5	5	4.95			4.95	5	-	-	V
	-	0.10	10	9.95			9.95	10	-	-	
	-	0.15	15	14.95			14.95	-	-	-	
Input Current, I <sub>IN</sub> Max.	-	0.18	18	±0.1	±0.1	±1	±1	-	±10 <sup>-5</sup>	±0.1	μA

## DYNAMIC ELECTRICAL CHARACTERISTICS

At T<sub>A</sub> = 25°C; Input t<sub>r</sub>, t<sub>f</sub> = 20 ns, C<sub>L</sub> = 50 pF, R<sub>L</sub> = 200kΩ

CHARACTERISTIC	TEST CONDITIONS	LIMITS			UNITS
		V <sub>DD</sub> VOLTS	TYP.	MAX.	
Propagation Delay Time: t <sub>PHL</sub> t <sub>PLH</sub>		5	190	380	ns
		10	90	180	
		15	65	130	
Transition Time, t <sub>THL</sub> t <sub>TLH</sub>		5	100	200	ns
		10	50	100	
		15	40	80	
Input Capacitance, C <sub>IN</sub>	Any Input		5	7.5	pF

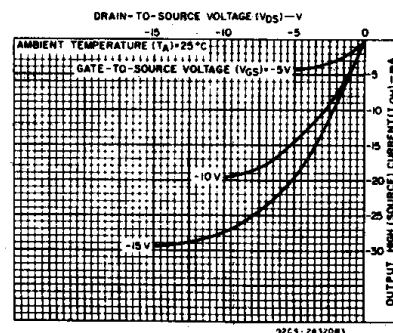


Fig. 8 - Typical output high (source) current characteristics.

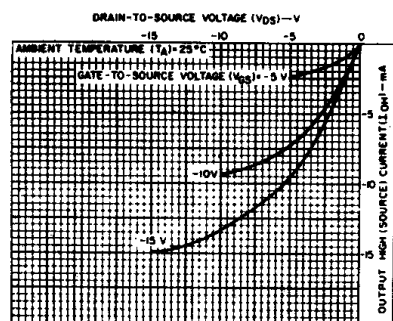


Fig. 9 - Minimum output high (source) current characteristics.

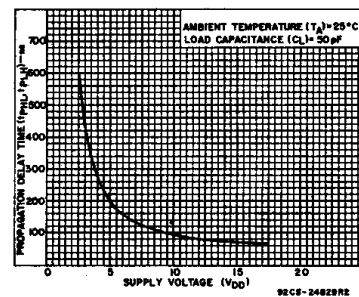


Fig. 10 - Typical propagation delay time vs. supply voltage.

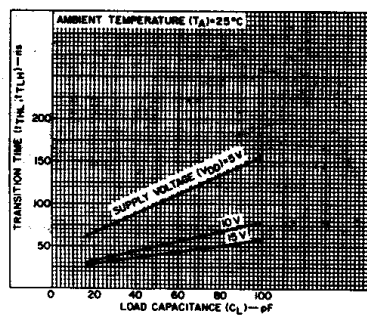


Fig. 11 - Typical transition time vs. load capacitance.

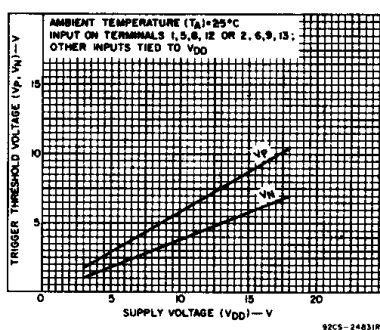


Fig. 12 - Typical trigger threshold voltage vs. V<sub>DD</sub>

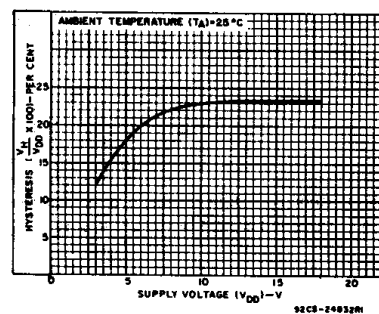


Fig. 13 - Typical per cent hysteresis vs. supply voltage.

# CD4093B Types



Fig. 14 - Typical power dissipation vs. frequency characteristics.

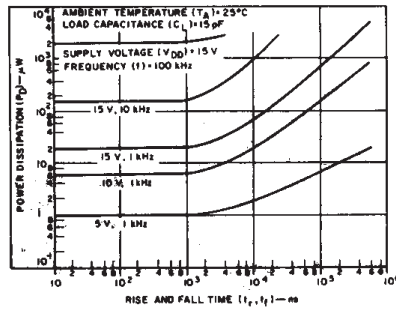


Fig. 15 - Typical power dissipation vs. rise and fall times.

## APPLICATIONS



Fig. 16 - Wave shaper.



Fig. 17 - Monostable multivibrator.

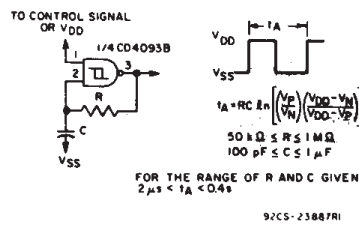


Fig. 18 - Astable multivibrator.

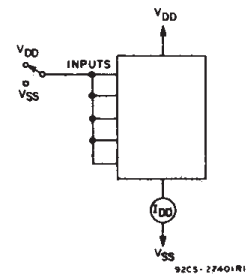


Fig. 19 - Quiescent device current test circuit.

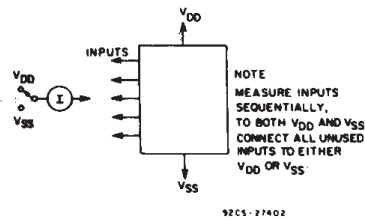
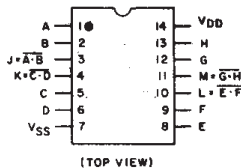


Fig. 20 - Input current test circuit.



TERMINAL ASSIGNMENT

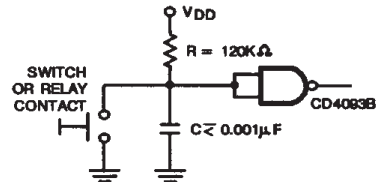


Fig. 21 - Contact Debouncer

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



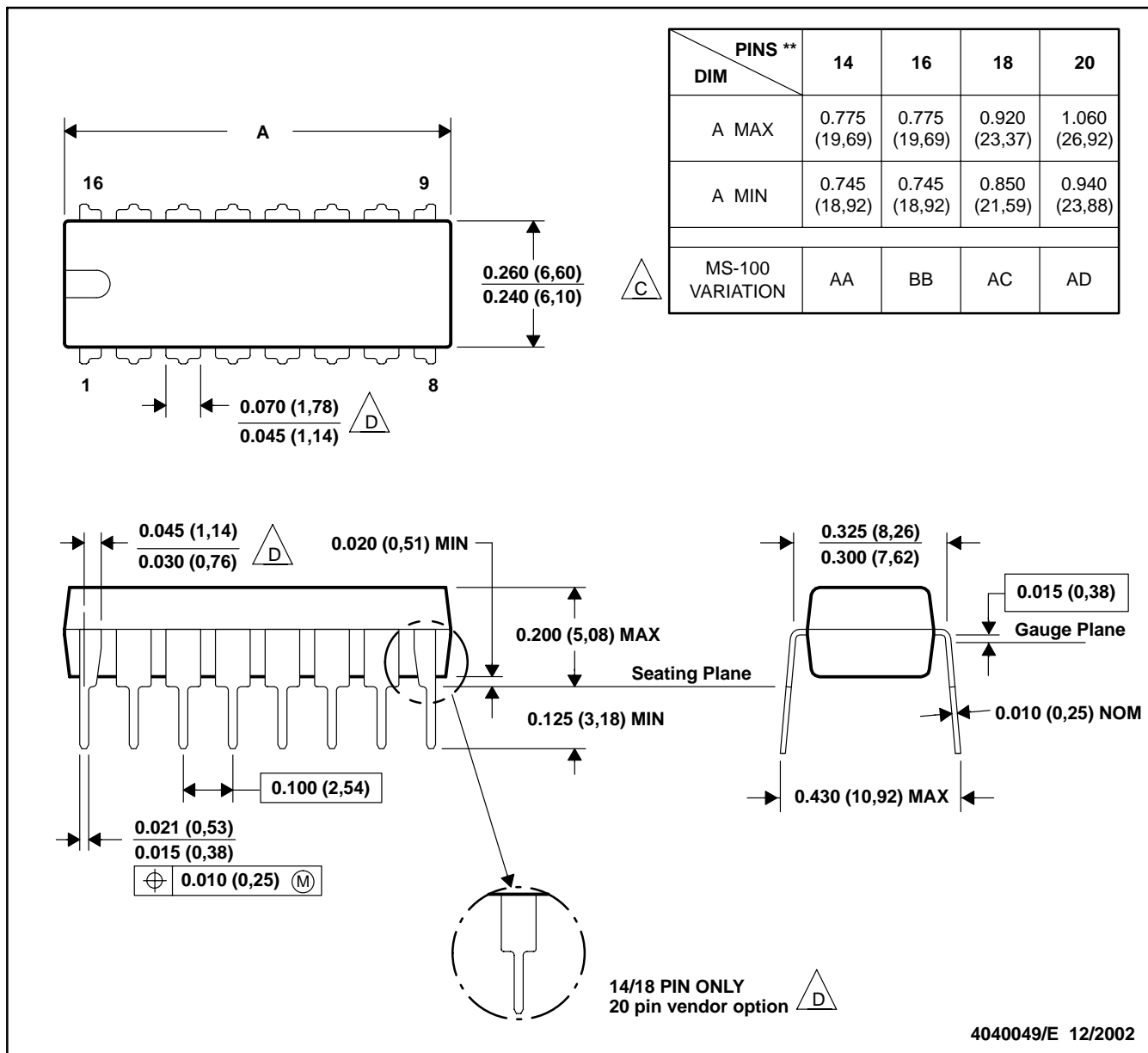
4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).  
 D The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

8 PINS SHOWN



4040047/E 09/01

- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).  
 D. Falls within JEDEC MS-012

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



PW (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

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